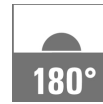


USB-MIC2.0B S1V 1N1 RL BK**Weidmüller Interface GmbH & Co. KG**

Klingenbergstraße 26

D-32758 Detmold

Germany

www.weidmueller.com**General ordering data**

Version	OMNIMATE Data - USB jack, PCB plug-in connector, USB 2.0, USB jacks, Type B, 480 Mbps, SMD solder connection, 180°, Plugging cycles: ≥ 10000 , Pitch in mm (P): 0.65, Number of poles: 5, LCP, $\leq 1 \mu''$ Au, Tape
Order No.	2762070000
Type	USB-MIC2.0B S1V 1N1 RL BK
GTIN (EAN)	4064675035299
Qty.	2,000 pc(s).
Packaging	Tape

Creation date August 29, 2024 8:44:52 PM CEST

Catalogue status 17.08.2024 / We reserve the right to make technical changes.

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Technical data

Dimensions and weights

Depth	2.9 mm	Depth (inches)	0.114 inch
Height	10.51 mm	Height (inches)	0.414 inch
Width	7.99 mm	Width (inches)	0.315 inch
Net weight	0.299 g		

System specifications

LED	No	Mounting onto the PCB	SMD solder connection
Number of poles	5	Outgoing elbow	180°
Performance-Category	480 Mbps	Pitch in inches (P)	0.026 "
Pitch in mm (P)	0.65 mm	Plugging cycles	≥ 10000
Plugging force/pole, max.	35 N	Product family	OMNIMATE Data - USB jack
Protection degree	IP20	Pulling force / pole, min.	10 N
Shield surface	nickel-plated	Shielding	Yes
Shielding material	Stainless steel	Solder pin dimensions	Octagonal
Solder pin length (l)	0 mm	Soldering process	Reflow soldering, Manual soldering
Tolerance of solder pin position	± 0.1 mm	Transmission rate	480 Mbps
Type of connection	Socket connector		

Electrical properties

Dielectric strength, contact / contact	100 V AC	Insulation strength	≥ 100 MΩ
Rated current	1 A	Rated voltage	48 V
Volume resistance	<25 mΩ		

Material data

Insulating material	LCP	Colour	black
Colour chart (similar)	RAL 9011	Insulation strength	≥ 100 MΩ
Moisture Level (MSL)	1	UL 94 flammability rating	V-0
Contact base material	Copper alloy	Contact material	Cu-alloy
Contact surface	Gold over nickel	Layer structure of plug contact	≤ 1 μ" Au
Storage temperature, min.	-40 °C	Storage temperature, max.	70 °C
Operating temperature, min.	-30 °C	Operating temperature, max.	80 °C

Packing

Packaging	Tape	VPE length	462 mm
VPE width	450 mm	VPE height	166 mm

Classifications

ETIM 6.0	EC002637	ETIM 7.0	EC002637
ETIM 8.0	EC002637	ETIM 9.0	EC002637
ECLASS 9.0	27-44-04-02	ECLASS 9.1	27-44-04-02
ECLASS 10.0	27-44-04-02	ECLASS 11.0	27-46-02-01
ECLASS 12.0	27-46-02-01	ECLASS 13.0	27-46-02-01
ECLASS 14.0	27-46-02-01		

Environmental Product Compliance

REACH SVHC	/
RoHS Compliance Status	Compliant without exemption

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www.weidmueller.com**Technical data****Approvals**

ROHS

Conform

Downloads

Engineering Data

[CAD data – STEP](#)

Product Change Notification

[Änderung der Verpackung – 2762070000 USB-MIC2.0B S1V 1N1 RL BK](#)[Change of packaging – 2762070000 USB-MIC2.0B S1V 1N1 RL BK](#)

Catalogues

[Catalogues in PDF-format](#)

USB-MIC2.0B S1V 1N1 RL BK

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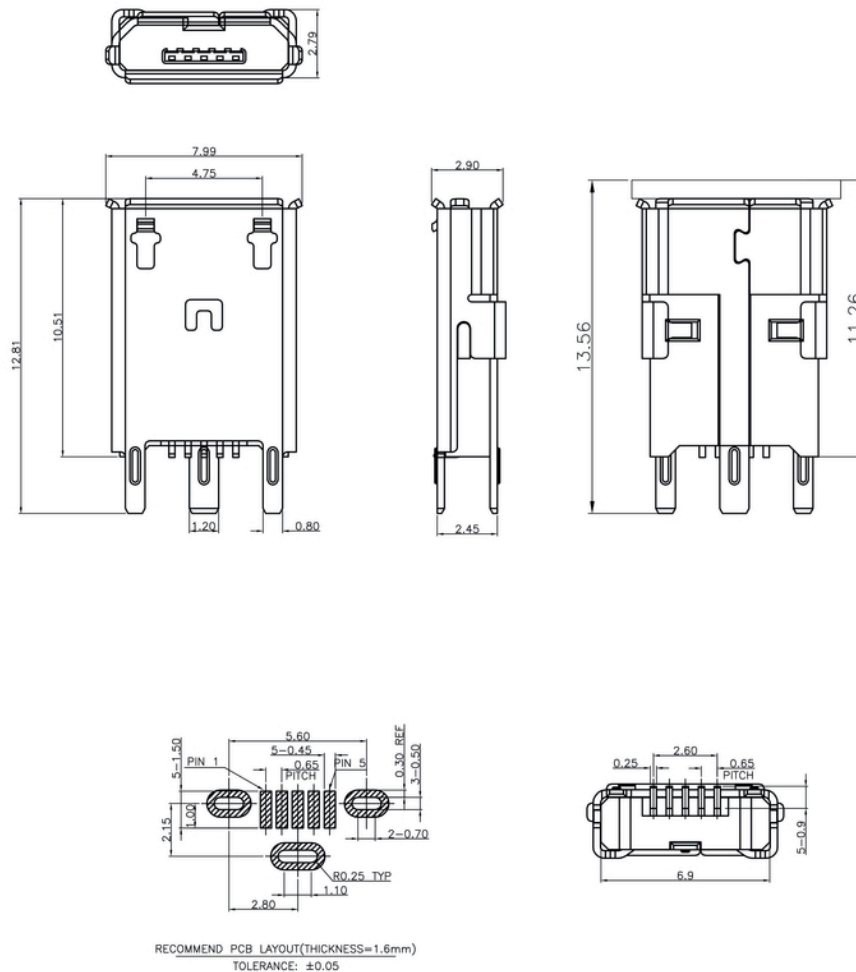
Drawings



USB-MIC2.0B S1V 1N1 RL BK

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Drawings

Recommended reflow soldering profile

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Reflow soldering profile

The perfect soldering profile for SMT Surface Mount Technology is one the most exiting question in SMT production. But there are more than one correct answer: The diagram of temperature-on-time is related to processing features of solder paste and to maximum load of components.

We have to consider the following parameters:

- Time for pre heating
- Maximum temperature
- Time above melting point
- Time for cooling
- Maximum heating rate
- Maximum cooling rate

We recommend a typical solder profile with associated process limits. With preheating components and board are prepared smoothly for the solder phase. Heating rate is typically $\leq +3\text{K/s}$. In parallel the solder paste is 'activated'. The time above melting point of 217°C the paste gets liquid and components and boards begin to connect. The maximum temperature of 245°C to 254°C should stay between 10 and 40 seconds. In the cooling phase at $\geq -6\text{K/s}$ solder is cured. Board and components cool down while avoiding cold cracks.